

## MOSFET

### 650V CoolMOS™ C6 Power Transistor

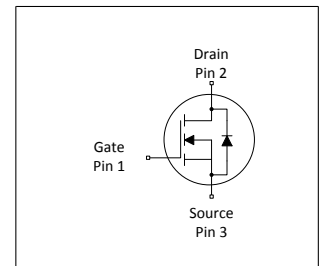
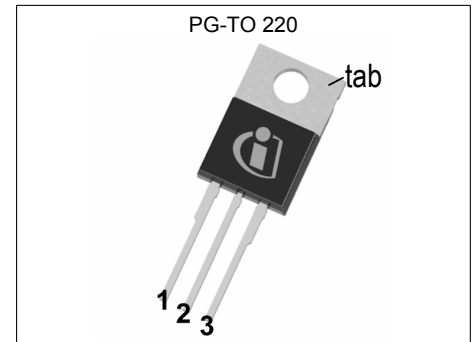
CoolMOS™ is a revolutionary technology for high voltage power MOSFETs, designed according to the superjunction (SJ) principle and pioneered by Infineon Technologies. CoolMOS™ C6 series combines the experience of the leading SJ MOSFET supplier with high class innovation. The resulting devices provide all benefits of a fast switching SJ MOSFET while not sacrificing ease of use. Extremely low switching and conduction losses make switching applications even more efficient, more compact, lighter and cooler.

#### Features

- Extremely low losses due to very low FOM  $R_{ds(on)} \cdot Q_g$  and Eoss
- Very high commutation ruggedness
- Easy to use/drive
- Pb-free plating, Halogen free mold compound
- Qualified for industrial grade applications according to JEDEC (J-STD20 and JESD22)

#### Potential applications

PFC stages, hard switching PWM stages and resonant switching PWM stages for e.g. PC Silverbox, Adapter, LCD & PDP TV, Lighting, Server, Telecom, UPS and Solar.



**Table 1 Key Performance Parameters**

Parameter	Value	Unit
$V_{DS} @ T_{j,max}$	700	V
$R_{DS(on),max}$	0.074	$\Omega$
$Q_g,typ$	138	nC
$I_D,pulse$	151	A
$E_{oss} @ 400V$	10.8	$\mu J$
Body diode $di/dt$	300	A/ $\mu s$

Type / Ordering Code	Package	Marking	Related Links
IPP65R074C6	PG-TO 220-3	65C6074	see Appendix A

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## 1 Maximum ratings

at  $T_j = 25^\circ\text{C}$ , unless otherwise specified

**Table 2 Maximum ratings**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Continuous drain current <sup>1)</sup>	$I_D$			57.7	A	$T_C = 25^\circ\text{C}$
				31.6		$T_C = 100^\circ\text{C}$
Pulsed drain current <sup>2)</sup>	$I_{D,pulse}$			151	A	$T_C = 25^\circ\text{C}$
Avalanche energy, single pulse	$E_{AS}$			915	mJ	$I_D = 8.1\text{A}$ , $V_{DD} = 50\text{V}$
Avalanche energy, repetitive	$E_{AR}$			1.40	mJ	$I_D = 8.1\text{A}$ , $V_{DD} = 50\text{V}$
Avalanche current, repetitive	$I_{AR}$			8.1	A	
MOSFET dv/dt ruggedness	dv/dt			50	V/ns	$V_{DS} = 0 \dots 480\text{V}$
Gate source voltage	$V_{GS}$	-20		20	V	static
		-30		30		AC ( $f > 1\text{ Hz}$ )
Power dissipation (non FullPAK) PG-TO 220	$P_{tot}$			480.8	W	$T_C = 25^\circ\text{C}$
Operating and storage temperature	$T_j, T_{stg}$	-55		150	$^\circ\text{C}$	
Mounting torque (non FullPAK) PG-TO 220				60	Ncm	M3 and M3.5 screws
Continuous diode forward current	$I_S$			50.0	A	$T_C = 25^\circ\text{C}$
Diode pulse current	$I_{S,pulse}$			151	A	$T_C = 25^\circ\text{C}$
Reverse diode dv/dt <sup>3)</sup>	dv/dt			15	V/ns	$V_{DS} = 0 \dots 480\text{V}$ , $I_{SD} \leq I_D$ , $T_j = 25^\circ\text{C}$
Maximum diode commutation speed	$di_f/dt$			300	A/ $\mu\text{s}$	

<sup>1)</sup> Limited by  $T_{j,max}$ . Maximum duty cycle  $D=0.75$

<sup>2)</sup> Pulse width  $t_p$  limited by  $T_{j,max}$

<sup>3)</sup>  $V_{peak} < V_{(BR)DSS}$ ,  $T_j < T_{j,max}$ , identical low side and high side switch with same  $R_g$

## 2 Thermal characteristics

**Table 3 Thermal characteristics PG-TO 220**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	$R_{thJC}$			0.26	°C/W	
Thermal resistance, junction - ambient	$R_{thJA}$			62	°C/W	leaded
Soldering temperature, wavesoldering only allowed at leads	$T_{sold}$			260	°C	1.6 mm (0.063 in.) from case for 10s

### 3 Electrical characteristics

at  $T_j = 25^\circ\text{C}$ , unless otherwise specified

**Table 4 Static characteristics**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(BR)DSS}$	650			V	$V_{GS} = 0V, I_D = 1mA$
Gate threshold voltage	$V_{GS(th)}$	2.5	3	3.5	V	$V_{DS} = V_{GS}, I_D = 1.4mA$
Zero gate voltage drain current	$I_{DSS}$			5	$\mu A$	$V_{DS} = 650V, V_{GS} = 0V, T_j = 25^\circ C$
			50			$V_{DS} = 650V, V_{GS} = 0V, T_j = 150^\circ C$
Gate-source leakage current	$I_{GSS}$			100	nA	$V_{GS} = 20V, V_{DS} = 0V$
Drain-source on-state resistance	$R_{DS(on)}$		0.067	0.074	$\Omega$	$V_{GS} = 10V, I_D = 13.9A, T_j = 25^\circ C$
			0.173			$V_{GS} = 10V, I_D = 13.9A, T_j = 150^\circ C$
Gate resistance	$R_G$		0.6		$\Omega$	$f = 1MHz, \text{open drain}$

**Table 5 Dynamic characteristics**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input capacitance	$C_{iss}$		3020		pF	$V_{GS} = 0V, V_{DS} = 100V, f = 1MHz$
Output capacitance	$C_{oss}$		170		pF	
Effective output capacitance, energy related <sup>1)</sup>	$C_{o(er)}$		118		pF	$V_{GS} = 0V, V_{DS} = 0 \dots 480V$
Effective output capacitance, time related <sup>2)</sup>	$C_{o(tr)}$		580		pF	$I_D = \text{constant}, V_{GS} = 0V, V_{DS} = 0 \dots 480V$
Turn-on delay time	$t_{d(on)}$		11		ns	$V_{DD} = 400V, V_{GS} = 13V, I_D = 20.8A, R_G = 1.8\Omega$
Rise time	$t_r$		7		ns	
Turn-off delay time	$t_{d(off)}$		56		ns	
Fall time	$t_f$		4		ns	

**Table 6 Gate charge characteristics**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Gate to source charge	$Q_{gs}$		17		nC	$V_{DD} = 480V, I_D = 20.8A, V_{GS} = 0 \text{ to } 10V$
Gate to drain charge	$Q_{gd}$		71		nC	
Gate charge total	$Q_g$		138		nC	
Gate plateau voltage	$V_{plateau}$		5.5		V	

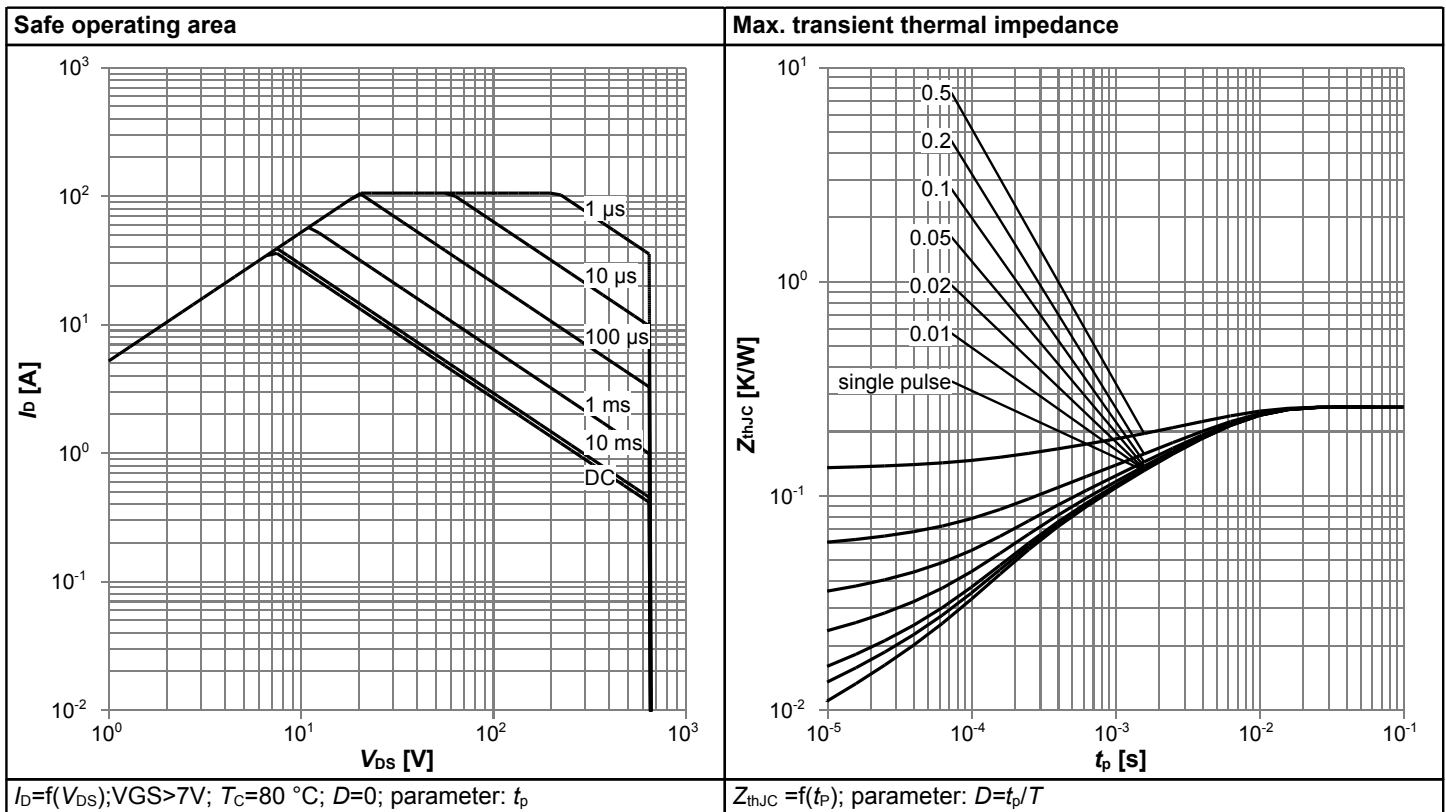
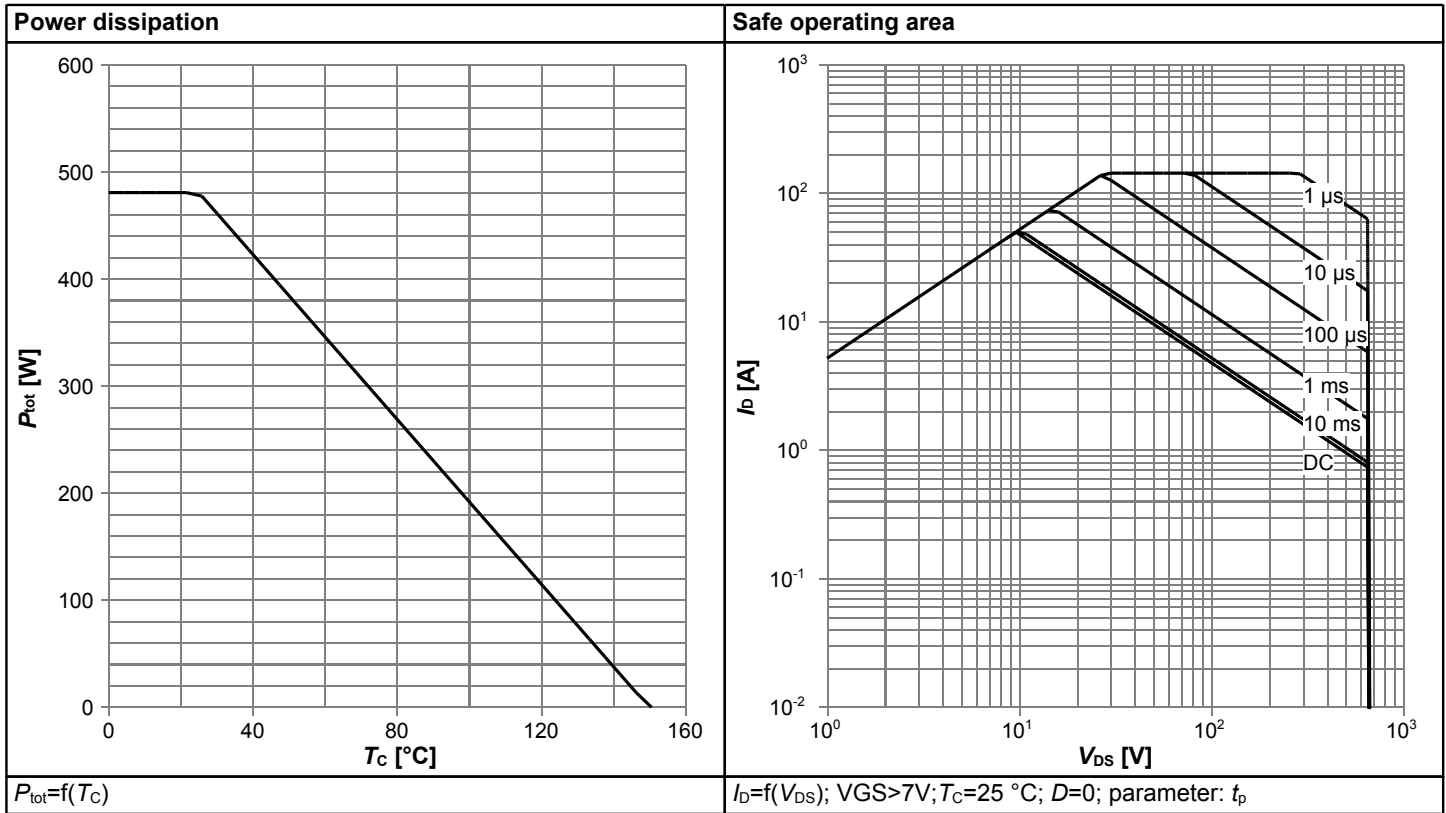
<sup>1)</sup>  $C_{o(er)}$  is a fixed capacitance that gives the same stored energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 to 80%  $V_{(BR)DSS}$

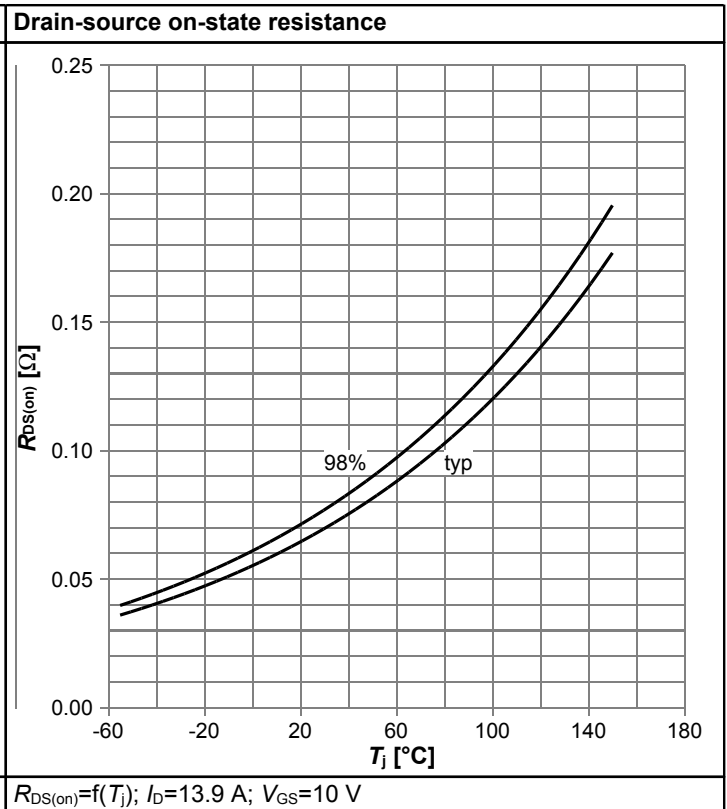
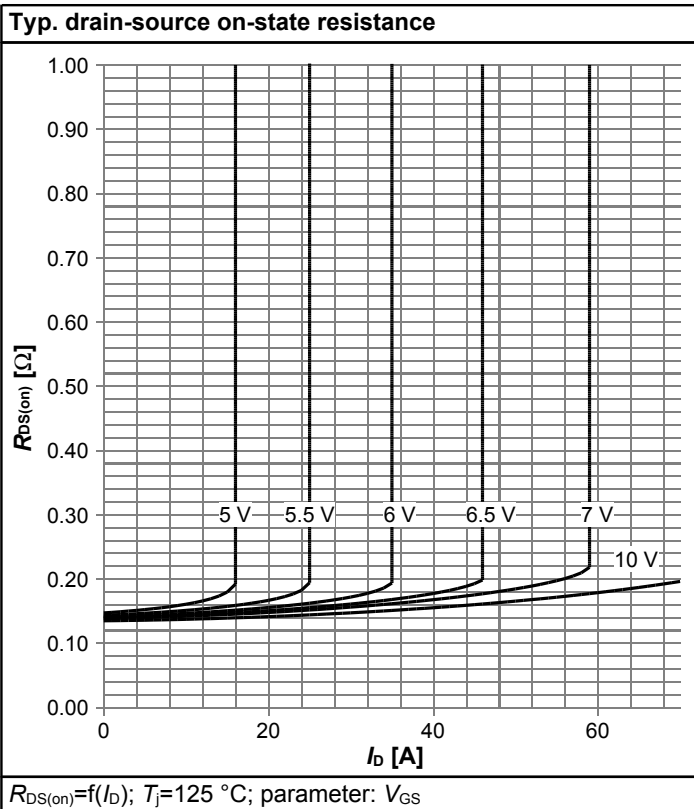
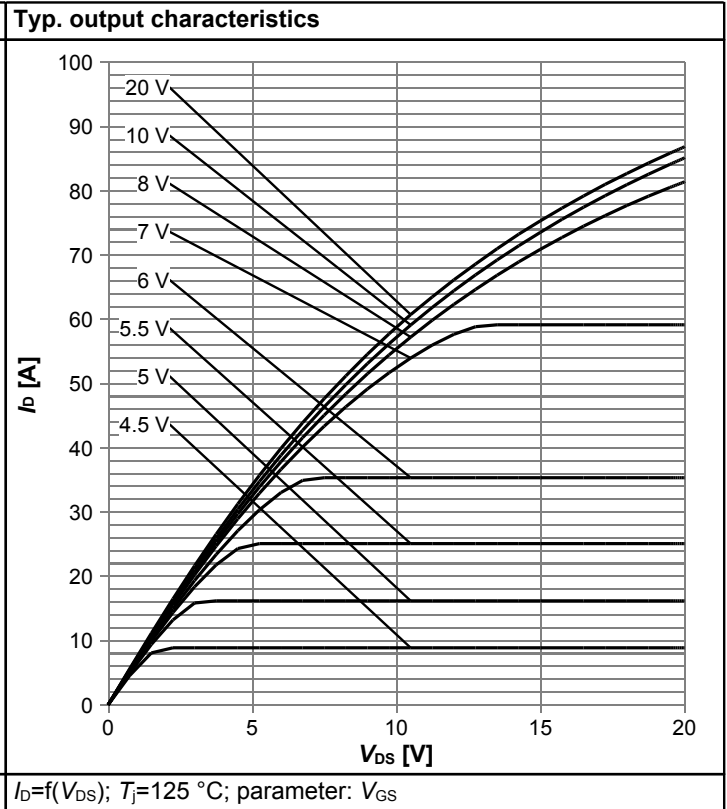
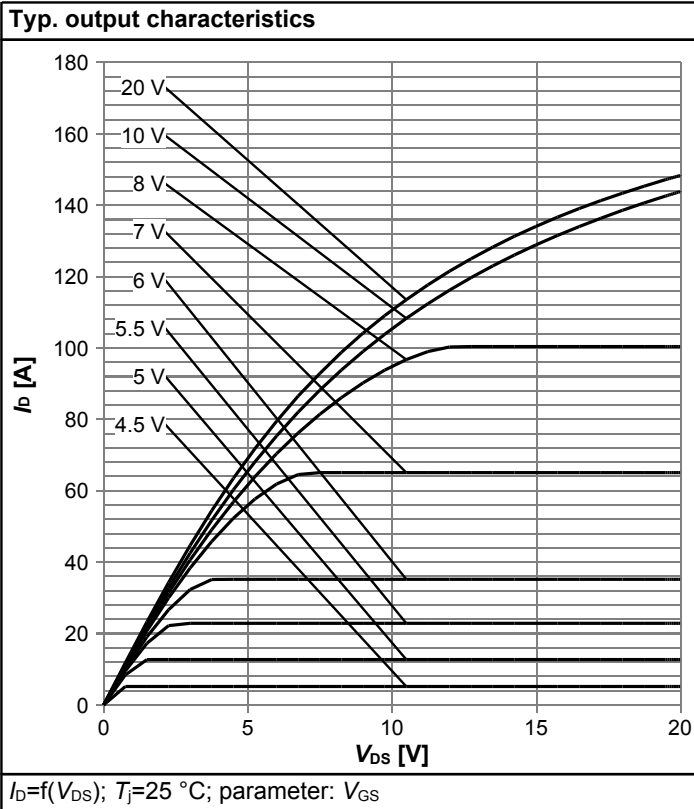
<sup>2)</sup>  $C_{o(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 to 80%  $V_{(BR)DSS}$

**Table 7 Reverse diode characteristics**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Diode forward voltage	$V_{SD}$		0.9		V	$V_{GS} = 0V, I_F = 20.8A, T_j = 25^\circ C$
Reverse recovery time	$t_{rr}$		560		ns	$V_R = 400V, I_F = 20.8A,$ $di_F/dt = 100A/\mu s$
Reverse recovery charge	$Q_{rr}$		12		$\mu C$	
Peak reverse recovery current	$I_{rrm}$		40		A	

### 4 Electrical characteristics diagrams

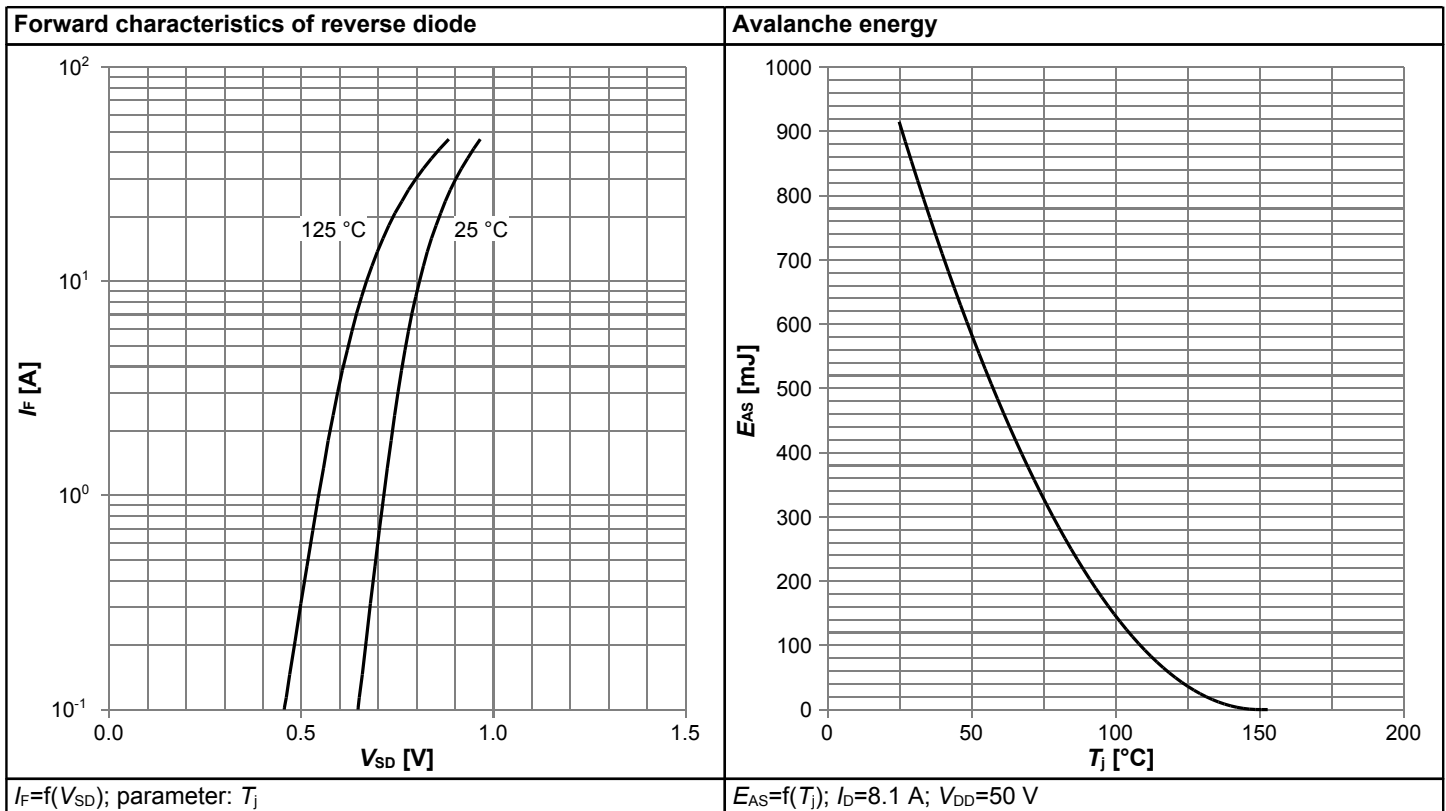
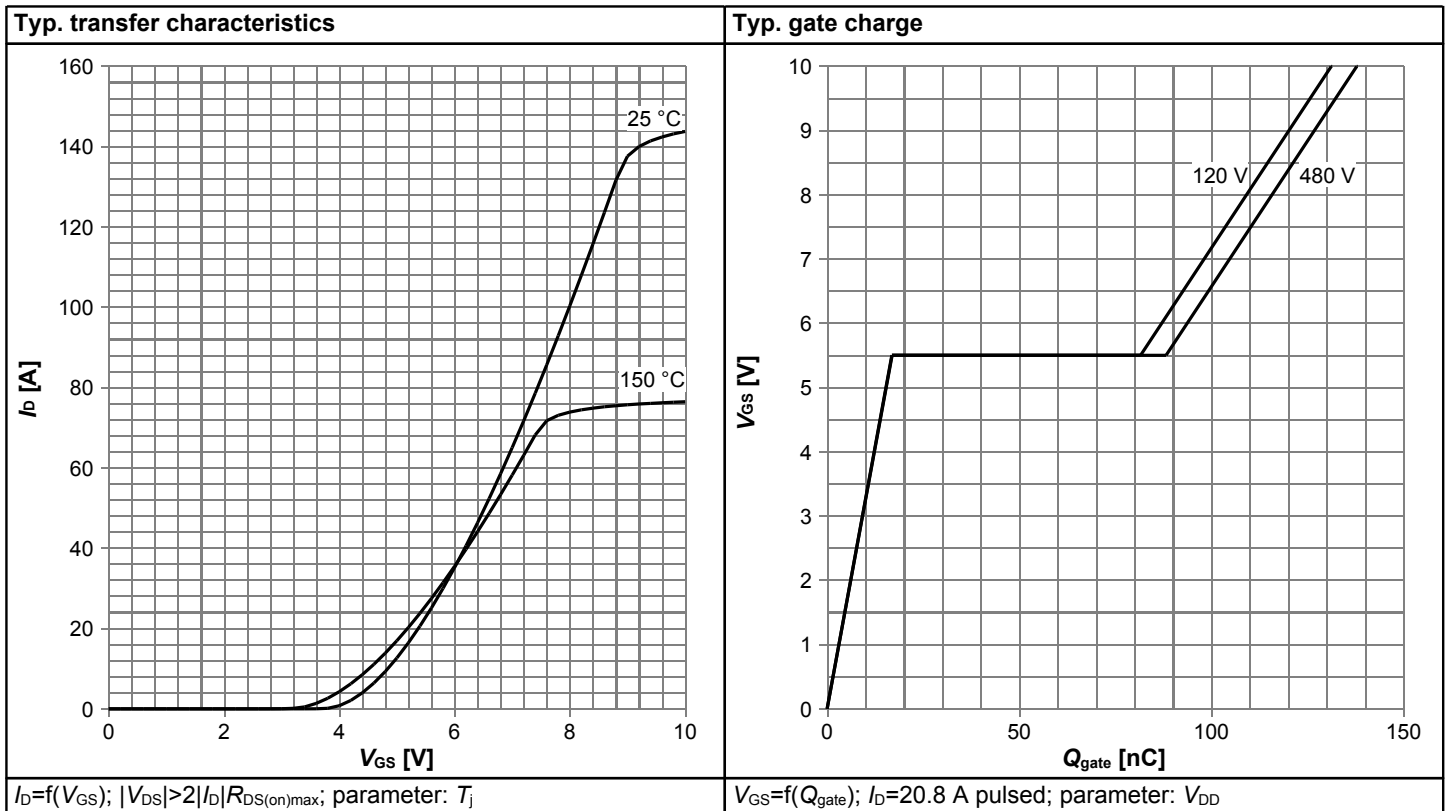




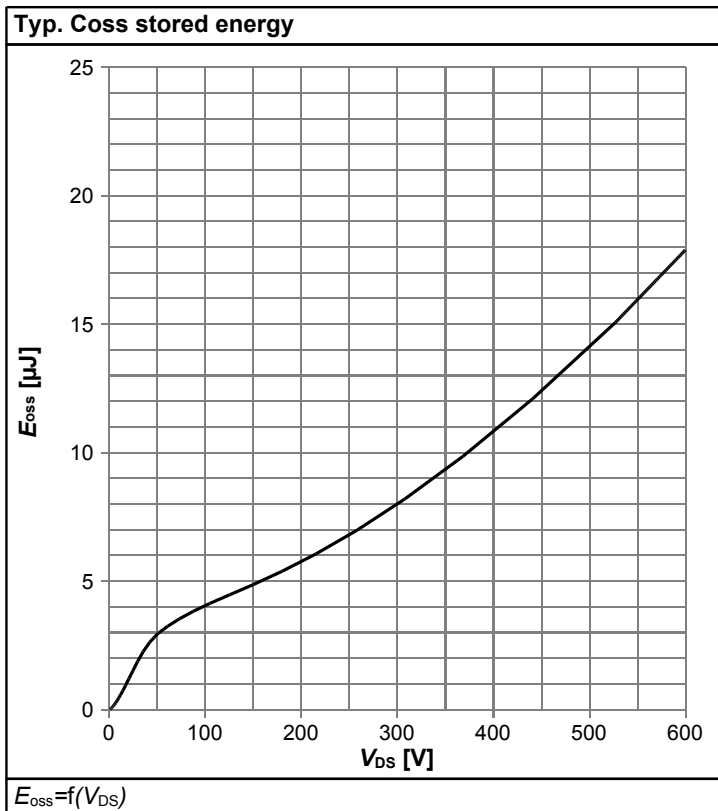
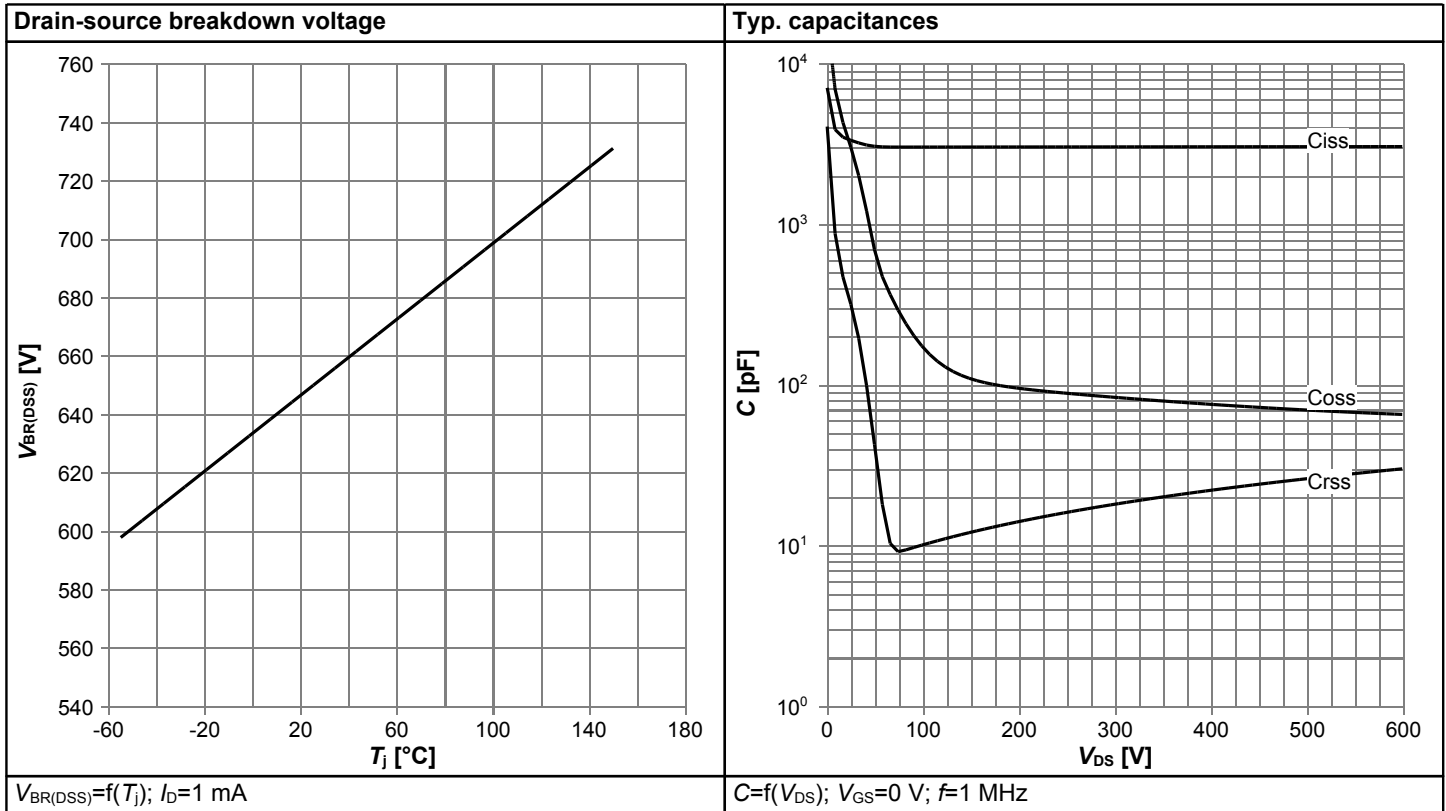


# 650V CoolMOS™ C6 Power Transistor

## IPP65R074C6



**650V CoolMOS™ C6 Power Transistor**  
**IPP65R074C6**



## 5 Test Circuits

**Table 8 Diode characteristics**



**Table 9 Switching times**



**Table 10 Unclamped inductive load**



## 6 Package Outlines



Figure 1 Outline PG-TO 220-3, dimensions in mm/inches

## 7 Appendix A

### Table 11 Related Links

- **IFX C6 Product Brief:** [www.infineon.com](http://www.infineon.com)
- **IFX C6 Portfolio:** [www.infineon.com](http://www.infineon.com)
- **IFX CoolMOS Webpage:** [www.infineon.com](http://www.infineon.com)
- **IFX Design Tools:** [www.infineon.com](http://www.infineon.com)

## Revision History

IPP65R074C6

**Revision: 2018-01-29, Rev. 2.2**

Previous Revision

Revision	Date	Subjects (major changes since last revision)
2.1	2011-09-14	Final Datasheet Release
2.2	2018-01-29	Changed I_GSS Test condition in Table 4, Page 6

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